

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) A laser-markable ~~tape structure~~ for marking a semiconductor device comprising:
a tape comprising a flexible film material; and
a multilayer adhesive including:
a first outermost adhesive layer comprising a mixture of electromagnetic radiation-curable components, ~~said the~~ electromagnetic radiation-curable components providing a laser-markable surface upon exposure to an electromagnetic radiation source by curing and bonding to at least a portion of a semiconductor device; and
a second adhesive layer disposed between ~~said the~~ tape and ~~said the~~ first outermost adhesive layer, the second adhesive layer comprising a mixture of electromagnetic radiation-curable components so that when exposed to radiation the second adhesive layer performs at least one of curing onto portions of the first outermost adhesive layer and losing adhesive properties for facilitating peeling of the flexible film material from at least a portion of a surface of a semiconductor device.
2. (Currently Amended) The laser-markable ~~tape structure~~ of claim 1, wherein ~~said the laser-markable tape structure~~ is adhered to at least a portion of a surface of a bare semiconductor die, the first outermost adhesive layer being disposed adjacent the surface of the bare semiconductor die.
3. (Currently Amended) The laser-markable ~~tape structure~~ of claim 2, wherein ~~said laser-markable tape is adhered to a~~ the at least a portion of the surface of a bare semiconductor die ~~surface subjected to a backgrinding process~~ has grinding marks therein.

4. (Currently Amended) The laser-markable ~~tape-structure~~ of claim 2, wherein ~~said the first outermost adhesive layer is cured upon exposure to said electromagnetic radiation source to thereby attach said first outermost adhesive layer permanently attached to said the~~ at least a portion of ~~said the~~ surface of ~~said the~~ bare semiconductor die when the radiation-curable components are in a cured state.

5. (Currently Amended) The laser-markable ~~tape-structure~~ of claim 4, wherein ~~said the curing of said first outermost adhesive layer results in a loss of adhesion between said first outermost adhesive layer and said second adhesive layer~~ laser-markable structure including a first bond strength between the tape and the at least a portion of the surface of the bare semiconductor die when the electromagnetic radiation-curable components are in an uncured state, and a second bond strength between the tape and the first outermost adhesive layer when the electromagnetic radiation-curable components are in a cured state, the second bond strength being lower than the first bond strength.

6. (Currently Amended) The laser-markable ~~tape-structure~~ of claim 4, wherein ~~said curing of said first outermost adhesive layer forms the laser-markable surface includes a substantially homogenous surface disposed over said the~~ at least a portion of ~~said the~~ surface of ~~said the~~ bare semiconductor die, the laser-markable surface being suitable for laser marking.

7. (Currently Amended) The laser-markable ~~tape-structure~~ of claim 3, wherein ~~said the second adhesive layer is cured by exposure to an electromagnetic radiation source~~ comprises radiation-curable components.

8. (Currently Amended) The laser-markable ~~tape-structure~~ of claim 1, wherein ~~said the~~ tape comprises a flexible film material having translucent properties.

9. (Currently Amended) A tape for use in the laser marking of a semiconductor device comprising:

a flexible film material; and

a multilayer adhesive including:

a first outermost adhesive layer comprising a mixture of electromagnetic radiation-curable components for providing a mark on a laser-markable surface upon exposure thereof to electromagnetic radiation by curing and bonding to at least a portion of a semiconductor device; and

a second adhesive layer disposed between ~~said the~~ flexible film material and ~~said the~~ first outermost adhesive layer, the second adhesive layer comprising a mixture of electromagnetic radiation-curable components so that when exposed to radiation the second adhesive layer performs at least one of curing onto portions of the first outermost adhesive layer and losing adhesive properties for facilitating peeling of the flexible film material from at least a portion of a surface of a semiconductor device.

10. (Currently Amended) The tape of claim 9, wherein ~~said tape includes a tape the~~ multilayer adhesive has a level of adhesiveness suitable for adhering the tape to at least a portion of a surface of a bare semiconductor die.

11. (Currently Amended) The tape of claim 10, wherein ~~said tape includes a tape for adhering to said the~~ portion of ~~said the~~ surface of ~~said the~~ bare semiconductor die ~~after backgrinding of said portion of said surface of said bare semiconductor die~~ has grinding marks therein.

12. (Currently Amended) The tape of claim 10, wherein ~~said the~~ first outermost adhesive layer ~~includes a first outermost adhesive layer for curing upon exposure to a source of electromagnetic radiation for attaching said first outermost adhesive layer is permanently attached to said the~~ at least a portion of ~~said the~~ surface of ~~said the~~ bare semiconductor die when the radiation-curable components are in a cured state.

13. (Currently Amended) The tape of claim 12, wherein ~~said the~~ second adhesive layer comprises radiation-sensitive components, the second adhesive layer comprising a first level of adhesiveness when the radiation-curable components of ~~curing of said the~~ first outermost adhesive layer are in an uncured state, and a second level of adhesiveness ~~provides a loss of adhesion between~~ when the radiation-curable components of ~~said the~~ first outermost adhesive layer and ~~said second adhesive layer~~ are in a cured state, the second level of adhesiveness being lower than the first level of adhesiveness.

14. (Currently Amended) The tape of claim 12, wherein ~~said curing of said first outermost adhesive layer forms the~~ laser-markable surface comprises a substantially homogenous surface disposed over ~~said the~~ at least a portion of ~~said the~~ surface of ~~said the~~ bare semiconductor die suitable for providing a mark by laser marking.

15. (Currently Amended) The tape of claim 11, wherein ~~said the~~ second adhesive layer is cured by exposure to electromagnetic radiation comprises radiation-curable components.

16. (Currently Amended) The tape of claim 9, wherein ~~said the~~ flexible film material comprises a flexible film material having translucent properties.

17. (Currently Amended) A tape for use in the marking of a semiconductor device comprising:

film material; and

at least two layers of adhesive including:

a first outermost adhesive layer comprising a mixture of electromagnetic

radiation-curable components for providing a mark on a surface upon exposure

thereof to electromagnetic radiation by curing and bonding to at least a portion of a semiconductor device; and

a second adhesive layer disposed between ~~said the~~ film material and ~~said the~~ first

outermost adhesive layer, the second adhesive layer comprising a mixture of

electromagnetic radiation-curable components so that when exposed to radiation

the second adhesive layer performs at least one of curing onto portions of the first outermost adhesive layer and losing adhesive properties for facilitating peeling of

the flexible film material from at least a portion of a surface of a semiconductor device.

18. (Currently Amended) The tape of claim 17, wherein ~~said tape includes a tape the~~ first outermost adhesive layer has a level of adhesiveness suitable for adhering the tape to at least a portion of a surface of a bare semiconductor die.

19. (Currently Amended) The tape of claim 18, wherein ~~said tape includes a tape for adhering to said the~~ portion of said the surface of said the bare semiconductor die after a backgrinding process has grinding marks therein.

20. (Currently Amended) The tape of claim 18, wherein ~~said the first outermost adhesive layer includes a first outermost adhesive layer for curing upon exposure to electromagnetic radiation for attaching said first outermost adhesive layer is permanently attached to said the~~ at least a portion of said the surface of said the bare semiconductor die when the radiation-curable components are in a cured state.

21. (Currently Amended) The tape of claim 20, wherein ~~said curing of said first outermost adhesive layer provides a loss of adhesion between said first outermost adhesive layer and said second adhesive layer~~ the tape comprises a first bond strength between the film material and the at least a portion of the surface of the bare semiconductor die when the electromagnetic radiation-curable components are in an uncured state, and a second bond strength between the film material and the first outermost adhesive layer when the electromagnetic radiation-curable components are in a cured state, the second bond strength being lower than the first bond strength.

22. (Currently Amended) The tape of claim 20, wherein ~~said curing of said first outermost adhesive layer forms~~ the electromagnetic radiation-curable components form a substantially homogenous surface upon exposure to an electromagnetic radiation source, the substantially homogenous surface being disposed over ~~said the~~ at least ~~said the~~ portion of ~~said the~~ surface of a bare semiconductor die, the substantially homogenous surface being suitable for laser marking for forming a mark on ~~said the~~ surface of ~~said the~~ bare semiconductor die.

23. (Currently Amended) The tape of claim 19, wherein ~~said the~~ second adhesive layer includes a layer cured by exposure to comprises electromagnetic radiation-curable components.

24. (Currently Amended) The tape of claim 17, wherein ~~said the~~ film material comprises a film material having translucent properties.

IN THE DRAWINGS:

The attached drawing sheet includes changes to FIG. 5. This sheet replaces the previous drawing sheet that included FIG. 5.